

**Method for producing encapsulated chips****Abstract**

5

A method for producing encapsulated chips includes preparing a wafer with contacts projecting from a surface of the wafer. The wafer is disposed on a dicing substrate and diced into a plurality of spaced chips on the dicing substrate. The contacts are covered with a protection arrangement, then injection molding being conducted to introduce encapsulation material into the contacts and the trenches. Then the protection arrangement is removed so 10 that the contacts are exposed.